ASSOCIATION CONNECTINI ELECTRONICS INDUSTRIES	Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	nder both	This docum level parts, t	ent is a declara the declaration	ion of the succession of the s	ubstances s all lower	within the manufactur r level materials for w	rer listed i hich the 1	item. Note: it nanufacturer	the item is an as has engineering	sembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information				
Supplier Inform	ation													
Company name*			Company unique ID				Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type	
		NSI50350AST3G SI		SMC 350MA			2023-06-08		N	MY1		228.02	mg	Each
Manufacturing	Proccess Information	1						-	1				I	
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL R			L Rating	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU			U Alloy	Alloy 1			260 C 30		30	seconds 3				
Comments														
evel 1 - maximum ti	ime at peak temperature o	luring sol	dering is 10-3	0 seconds										
For more information	on regarding material com	position	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	1.34	mg	Supplier	Silicon (Si)	7440-21-3		1.34	mg	
Die Attach Solder	5.17	mg	Supplier	Silver (Ag)	7440-22-4		0.1293	mg	
			А	Lead (Pb)	7439-92-1	7a	4.7822	mg	
			Supplier	Tin (Sn)	7440-31-5		0.2585	mg	
Lead Frame	92.28	mg	Supplier	Zinc (Zn)	7440-66-6		0.0923	mg	
			Supplier	Iron (Fe)	7439-89-6		2.2147	mg	
			Supplier	Copper (Cu)	7440-50-8		89.973	mg	
Mold Compound-Black	126.72	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.672	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.6336	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		18.3744	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		82.368	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		12.672	mg	
Plating	2.51	mg	Supplier	Tin (Sn)	7440-31-5		2.51	mg	